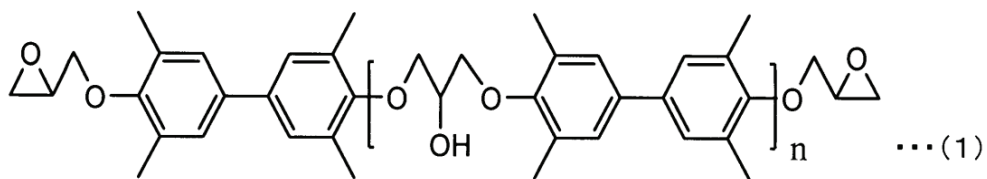


## ABSTRACT

The present invention relates to a tetramethylbiphenol epoxy resin represented by the following formula (1), which is an epoxy resin having excellent solvent solubility, a small hydrolyzable chlorine amount and further an appropriate melt viscosity and being effectively applicable, to a semiconductor sealing material and electrical or electronic components such as laminate sheet.

[Chem. 1]



(wherein  $n$  represents an integer of 0 to 10.)